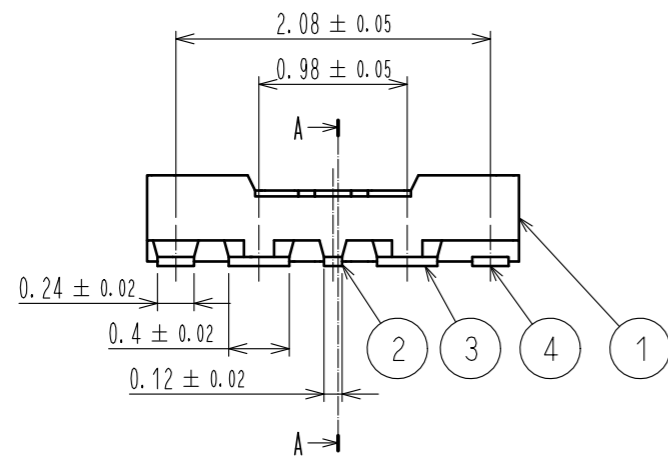
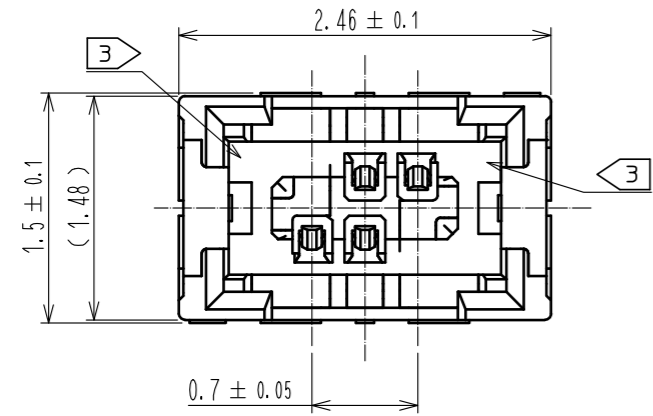
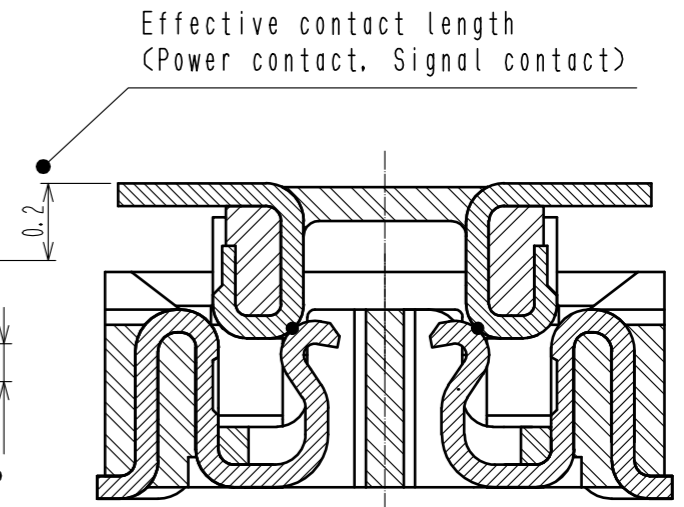
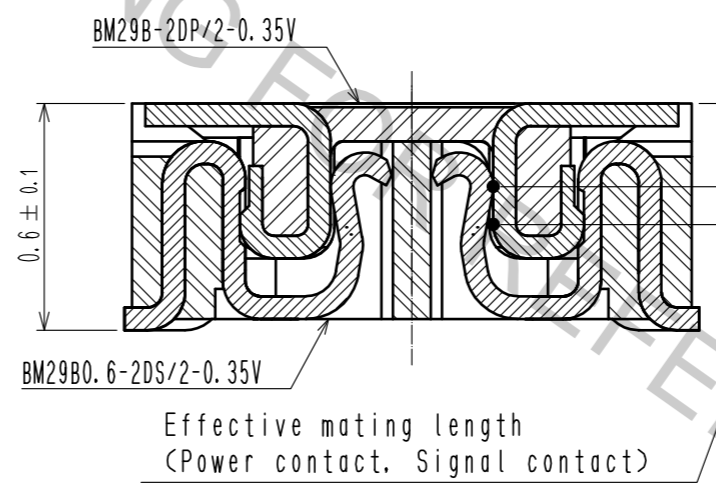
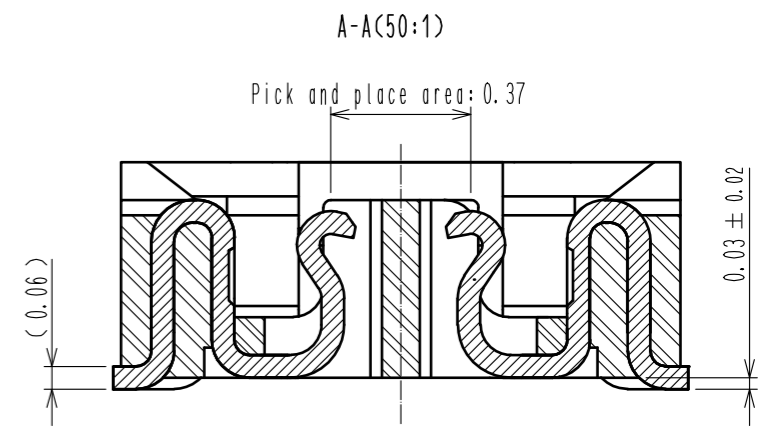
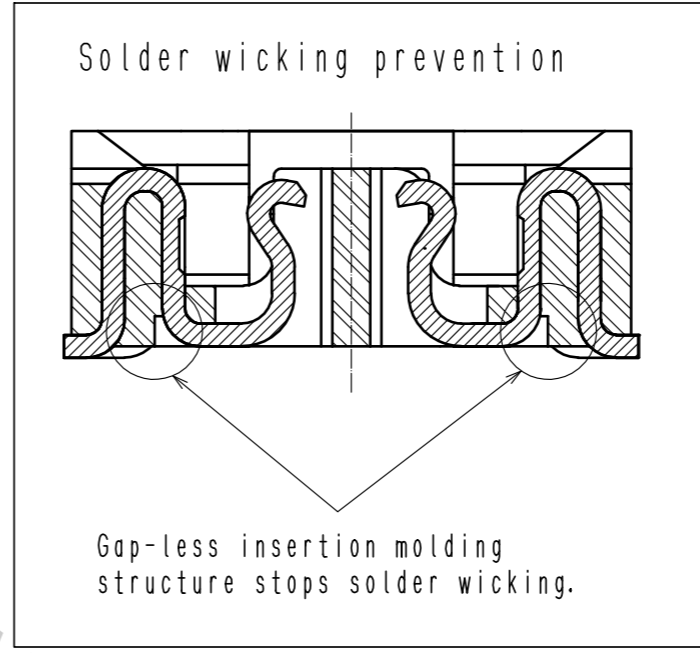


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HRS DRAWING REFERENCE



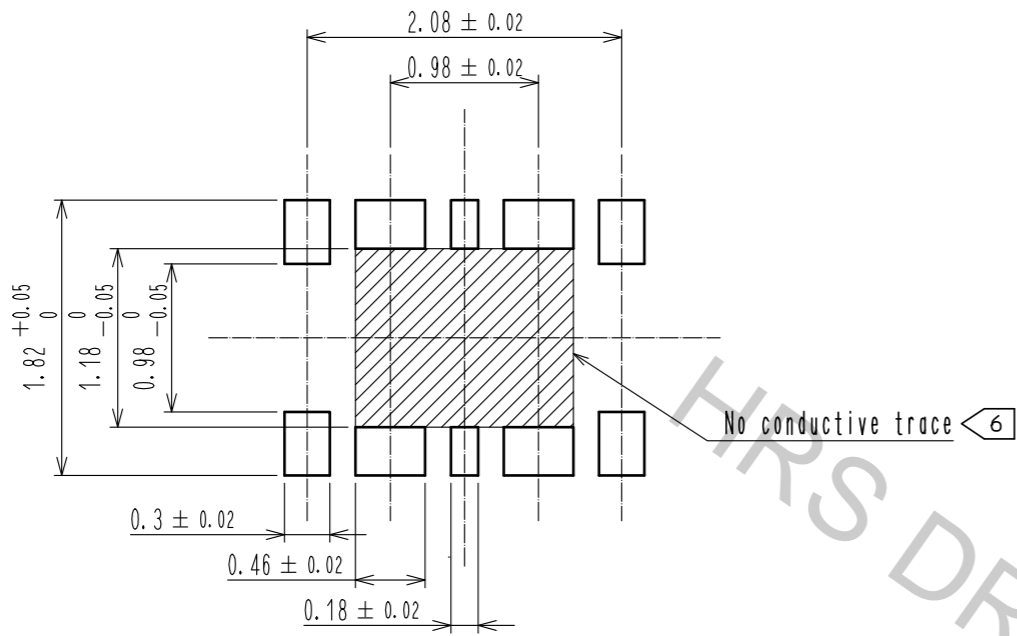
NOTE 1 . All lead co-planarity shall be 0.08mm MAX.
 2 . Contact plating specifications
 Contact area : Gold 0.05μm MIN
 SMT lead : Gold 0.05μm MIN
 Under plating : Nickel 1μm MIN
 (Surface : Sealing)
 3 . HRS mark and CAV No. are indicated in approx. position shown.

NO.	MATERIAL	FINISH .	REMARKS	NO.	MATERIAL	FINISH .	REMARKS
4	PHOSPHOR BRONZE	2		8	PS		CLEAR. REINFORCEMENT COLLAR
3	PHOSPHOR BRONZE	2		7	PS		BLACK. PLASTIC REEL
2	PHOSPHOR BRONZE	2		6	POLYESTER		CLEAR. COVER TAPE
1	LCP		UL94 V-0. BLACK	5	PS		SMOKE GRAY. EMBOSSED CARRIER TAPE

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	20:1	1				

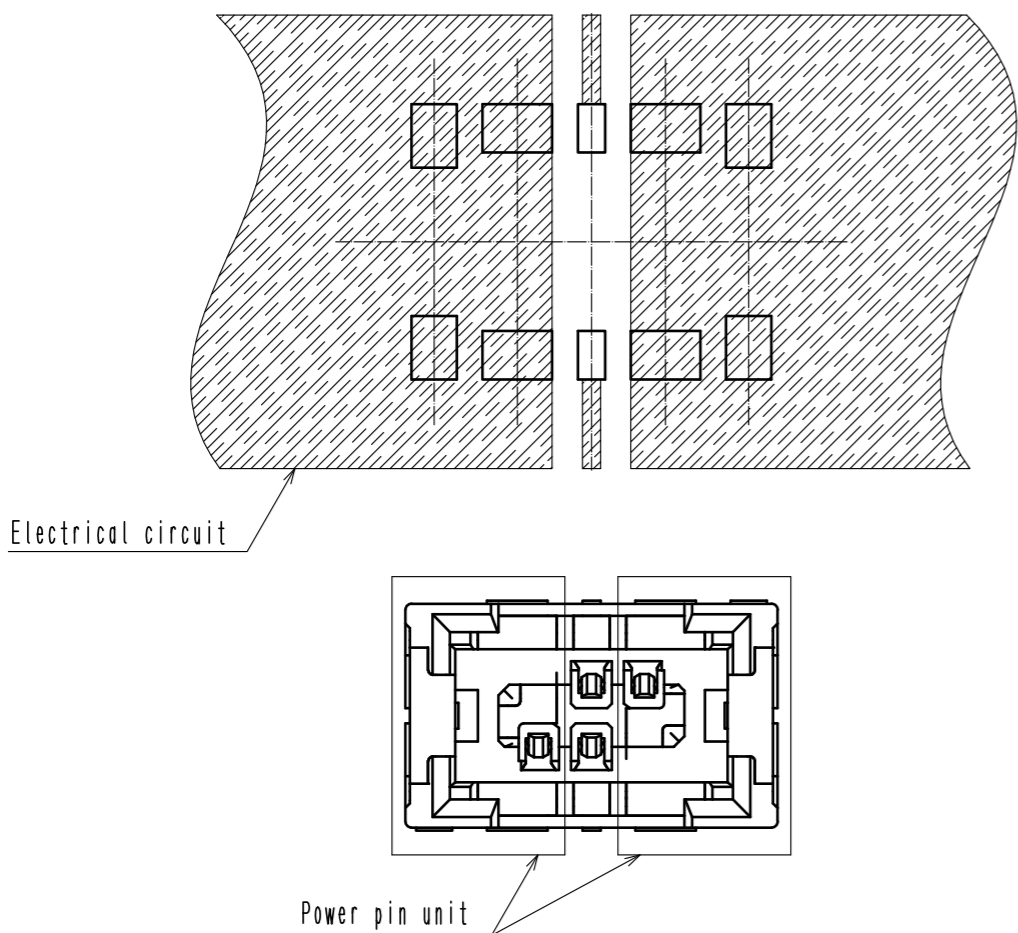
HRS HIROSE ELECTRIC CO., LTD.	APPROVED : MO. ISHIDA	16.01.06	DRAWING NO.	EDC-362699-53-01
	CHECKED : WR. FUKUCHI	16.01.06	PART NO.	BM29B0.6-2DS/2-0.35V(53)
	DESIGNED : TY. YAMASAKI	16.01.06	CODE NO.	CL673-7001-0-53
	DRAWN : KR. AJITO	16.01.06		

◆ Recommended PCB layout

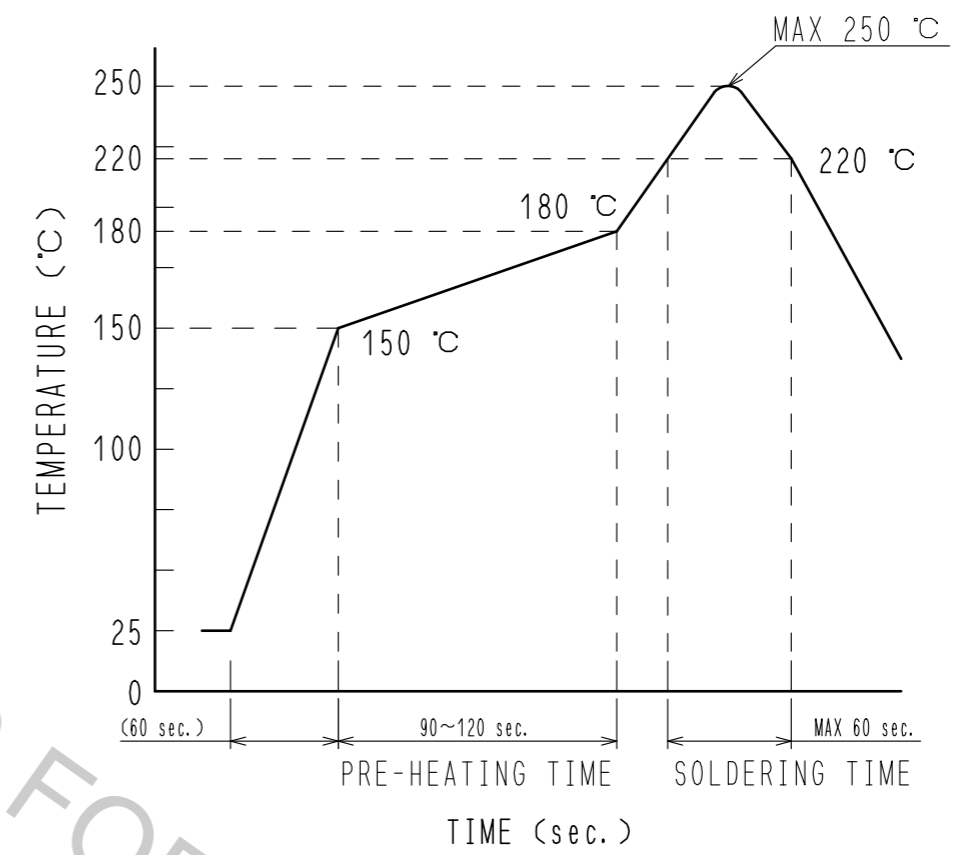


◆ Recommended metal mask dimensions
 Metal mask thickness : 100 μm
 (Open ratio : 100% for PCB layout)

◆ Recommended electrical circuit layout



4 Recommended reflow temperature profile using lead-free solder paste.



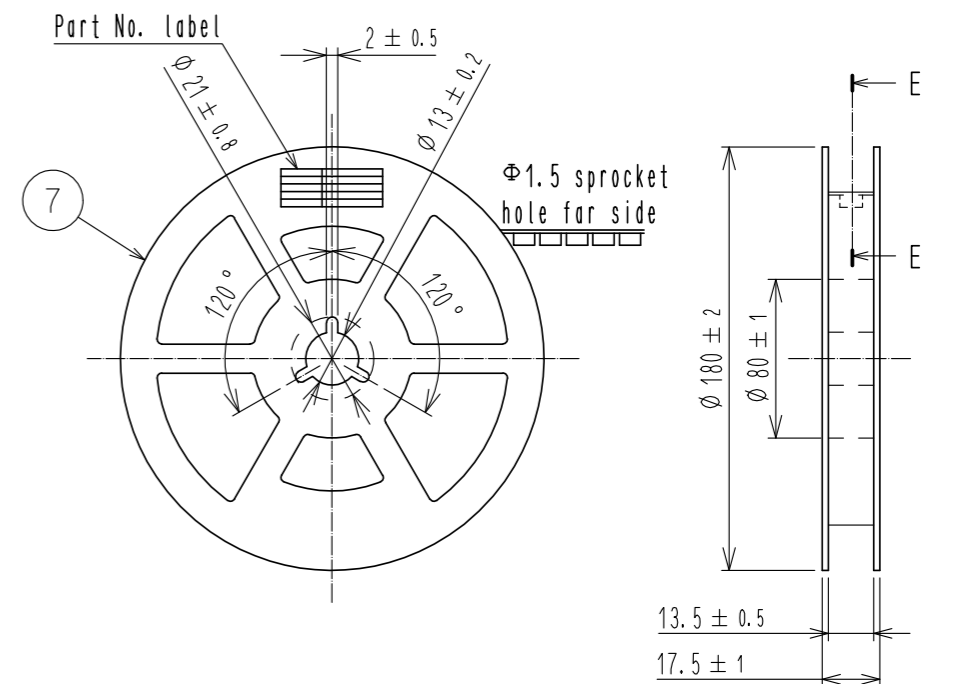
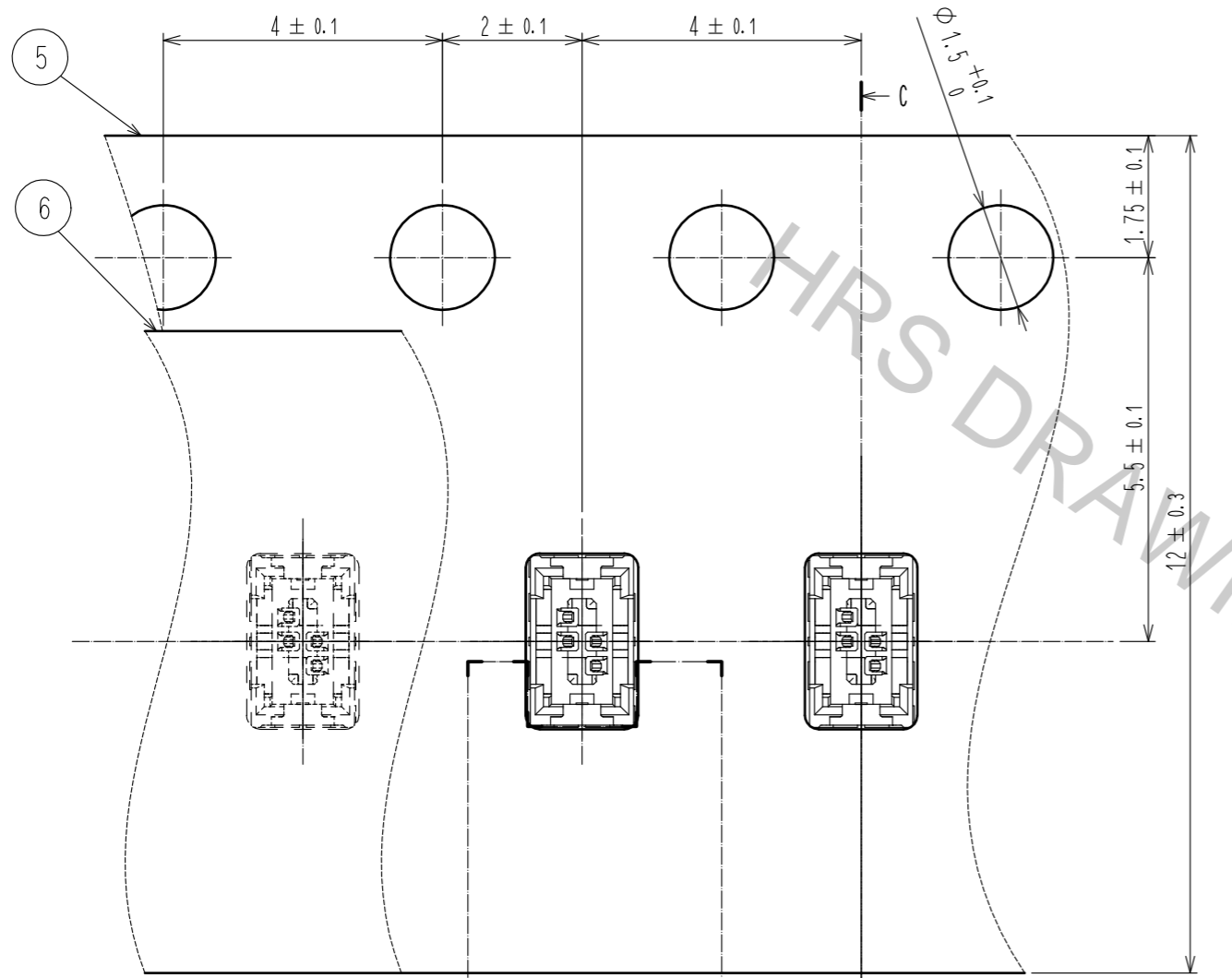
Reflow method: IR reflow
 Number of reflow cycles: 2 cycles MAX.
 1) Reflow time
 Duration above 220°C: 60 sec MAX.
 (Peak temperature: 250°C MAX)
 2) Pre-heat time
 Pre-heat temperature (MIN): 150°C
 Pre-heat temperature (MAX): 180°C
 Pre-heat time: 90-120 sec.

- 4 The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.
- 5 Please contact us in case you will make different settings from our recommendation.
- 6 For the routing on the indicated PCB surface, apply solder resist in order for the insulation treatment.

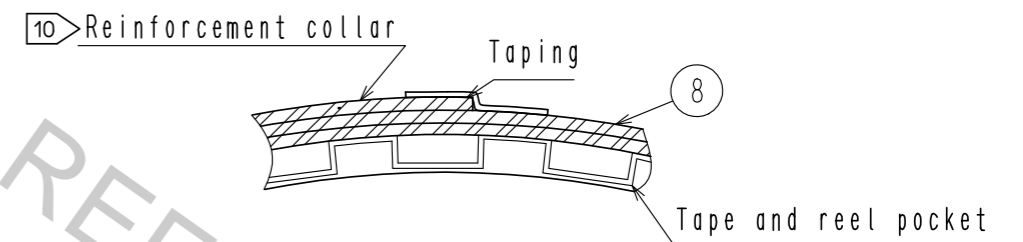
HRS	DRAWING NO.	EDC-362699-53-01	2/3
	PART NO.	BM29B0. 6-2DS/2-0.35V(53)	
	CODE NO.	CL673-7001-0-53	

Embossed carrier tape packaging (10:1)

Style and dimension of reel (Free)



E-E (Free)

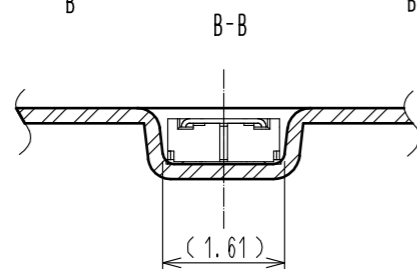
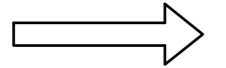


Detail of part No. label

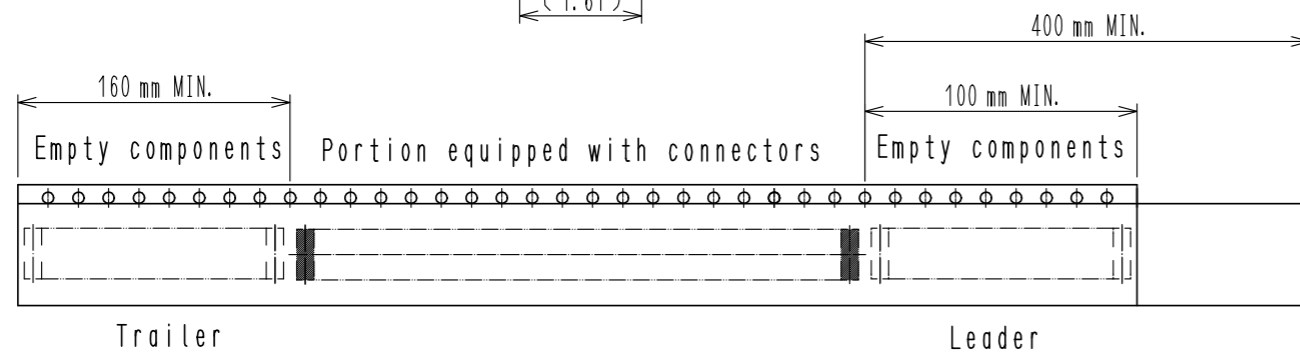
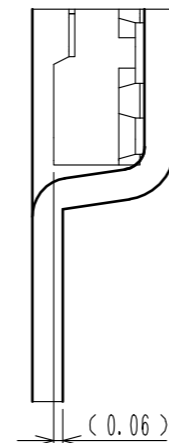
製造年月日	** ** *
製品コード	CL0673-7001-0-53
製品名	BM29B0.6-2DS/2-0.35V(53)
数量	1,000
納入者	ヒロセ電機(株)

Data of manufactured
Code No.
Part No.
Quantity
Supplier

Direction of unreeling



D(20:1)



9 Taping (Free)

- 7 . Per reel 1,000 connectors.
- 8 . The dimensions in parentheses are for reference.
- 9 . Refer to JIS C 0806 and IEC60286-3
(Packaging of components for automatic handling)
- 10 . Wrap a reinforcing collar made by polystyrene to the surface of emboss reel at the termination side in order to protect emboss carrier tape, top cover tape.

HRS	DRAWING NO.	EDC-362699-53-01
	PART NO.	BM29B0.6-2DS/2-0.35V(53)
	CODE NO.	CL673-7001-0-53
		3/3